Report NO.: MG00001000161

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJQ4406A
Package Type :	SOP8

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.3816%
Lead Frame	Cu	7440-50-8	97.03%	44.7337%
	Fe	7439-89-6	2.21%	
	Pb	7439-92-1	0.01%	
	P	7723-14-0	0.08%	
	Zn	7440-66-6	0.02%	
	Ag	7440-22-4	0.66%	
Epoxy	Silver Powder	7440-22-4	78.997%	1.783%
	Epoxy resin	9003-36-5	5.993%	
	Diluent A	3101-60-8	3.989%	
	Diluent B	Trade Secret	4.265%	
	Diluent C	Trade Secret	2.10%	
	Hardener A	Trade Secret	1.692%	
	Hardener B	Trade Secret	2.887%	
	Solvent	Trade Secret	0.021%	
	Organic Peroxide	Trade Secret	0.056%	
Wire1	copper	7440-50-8	99.99%	0.3286%
	others	/	0.01%	
Wire2	Cu	7440-50-8	97.898%	0.2873%
	Pd	7440-05-3	1.98%	
	Au	7440-57-5	0.122%	
Mold Compound	Epoxy Resin1	Trade secret	6.80%	50.2777%
	Epoxy Resin2	Trade secret	4.70%	
	Phenol Resin	Trade secret	5.30%	
	Carbon Black	1333-86-4	0.20%	
	Amorphous silica	60676-86-0	83.00%	
Plating	Tin	7440-31-5	100.00%	2.2081%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.